

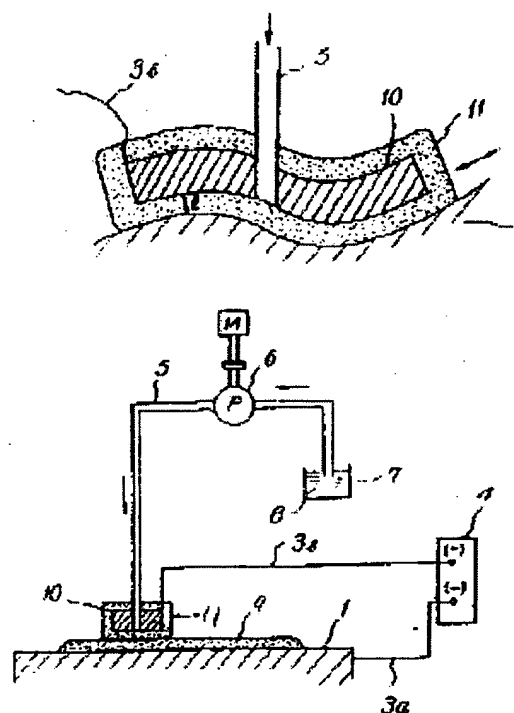
PARTIAL PLATING DEVICE

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 - **International:** C25D5/06
 - **European:**
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Abstract of JP1234590

PURPOSE:To form a uniform plated layer on the surface of a metallic base material by forming an anode of flexible conductive material and covering the periphery thereof with sponge in case of making the surface of the metallic base material, whose surface is not even but wavy, as a cathode and moving an anode in the upper part and electrifying both electrodes while feeding plating liquid so as to plate the metallic base material.

CONSTITUTION:In case of making a metallic base material 1 whose surface is not even but wavy as a cathode and feeding plating liquid 8 between an anode 10 and the base material 1 from a tank 7 while moving the anode 10 in the upper part thereof and electrifying both electrodes with an electric source 4 to form a plated layer 9 on the surface of the base material, the anode 10 is formed of spongelike graphite excellent in flexibility and conductivity and its periphery is covered with sponge 11. The anode 10 is deformed along the waviness of the surface of the base material and the distance (l) between the anode 10 and the surface of the base material 1 can be held constant with sponge 11. Therefore, the plated layer 9 free from fluctuation in thickness and being uniform can be formed.



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